SAW components

SAW RF filter

Automotive telematics
WLAN 2G

Series/type:	B4347
Ordering code:	B39242B4347P810
Date:	March 09, 2016
Version:	2.0

Table of contents

1 Application

- Low-loss RF filter for Bluetooth/WLAN
- Usable pass band 83.5MHz

2 Features

- Package size 1.4±0.1 mm × 1.1±0.1 mm
- Package height 0.45 mm (max.)
- Package code QCS5P
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- AEC-Q200 qualified component family
- Electrostatic Sensitive Device (ESD)

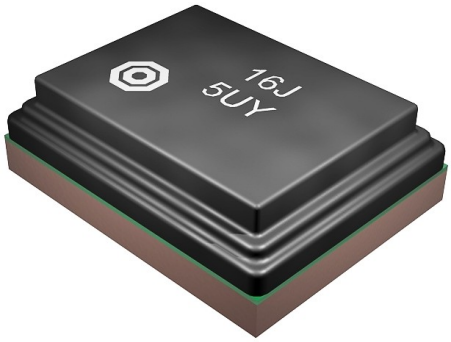

Figure 1: Picture of component with example of product marking.

3 Package

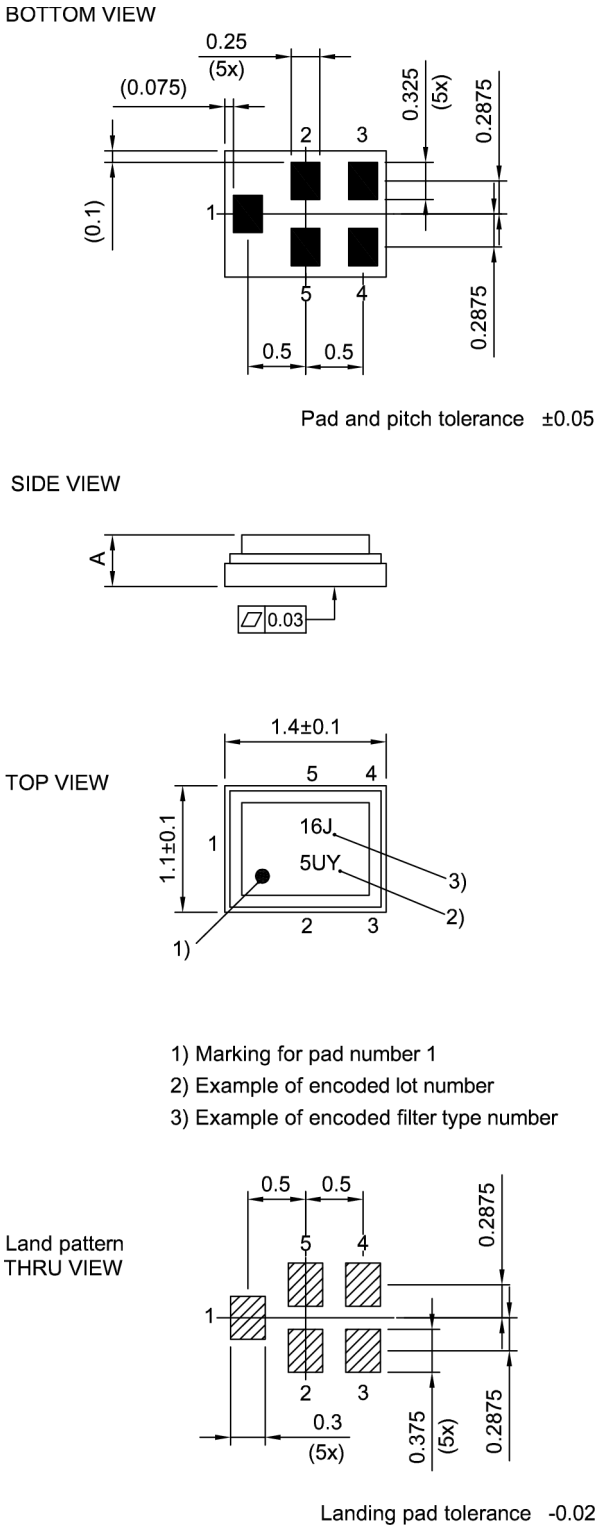

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Simplified drawings (p. 16).

4 Pin configuration

- 1 Input
- 4 Output
- 2, 3, 5 Ground

5 Matching circuit

■ L_{p1} = 4.3 nH ■ L_{p4} = 4.7 nH

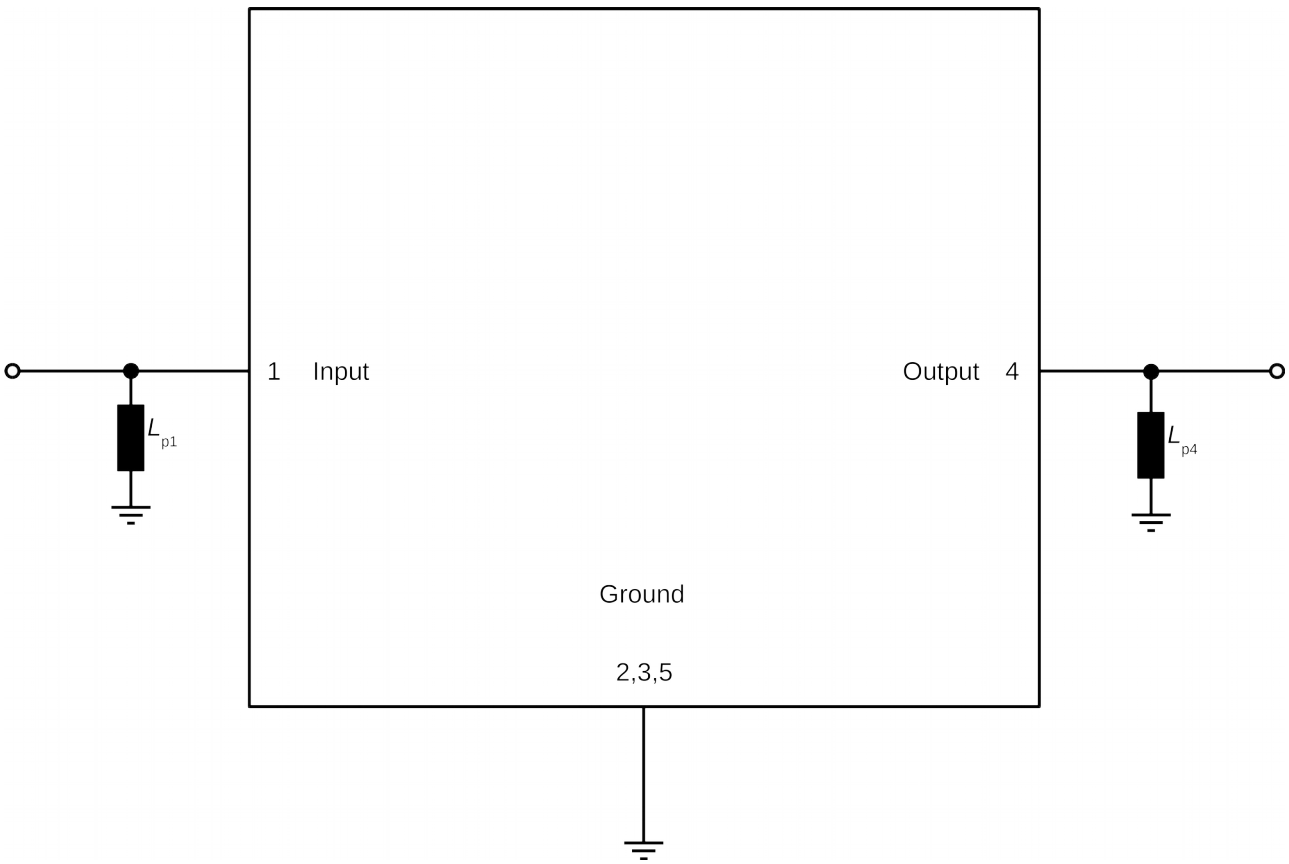

Figure 3: Schematic of matching circuit.

6 Characteristics

Temperature range for specification T_{SPEC} = −40 °C ... +105 °C
Input terminating impedance Z_{IN} = 50 Ω with par. 4.3 nH[1)]
Output terminating impedance Z_{OUT} = 50 Ω with par. 4.7 nH[1)]

Characteristics				min. for T_{SPEC}	typ. @+25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	2441.75	—	MHz
Maximum insertion attenuation			α_{max}				
	2400... 2483.5	MHz		—	1.8	2.7	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	2400... 2483.5	MHz		—	0.6	1.5	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	2400... 2483.5	MHz		—	1.6	2.2	
@ output port	2400... 2483.5	MHz		—	1.6	2.2	
Minimum attenuation			α_{min}				
	50... 1000	MHz		36	42	—	dB
	1000... 2100	MHz		28	33	—	dB
	2100... 2320	MHz		28	35	—	dB
	2320... 2332.5	MHz		38	44	—	dB
	2332.5... 2345	MHz		33	40	—	dB
	2600... 3100	MHz		30	40	—	dB
	3100... 4000	MHz		30	40	—	dB
	4000... 5000	MHz		37	45	—	dB

1) See Matching circuit (p. 5).

7 Maximum ratings

Operable temperature	T_{OP} = −40 °C ... +125 °C	
Storage temperature	T_{STG} = −40 °C ... +125 °C	
DC voltage	V_{DC} = 0 V	
Input power	P_{IN}	
@ input port: 2400 ... 2483.5 MHz	20 dBm	Continuous wave for 10000 h @ 55 °C.
@ input port: 2400 ... 2483.5 MHz	16 dBm	Continuous wave for 1000 h @ 125 °C.

8 Transmission coefficient

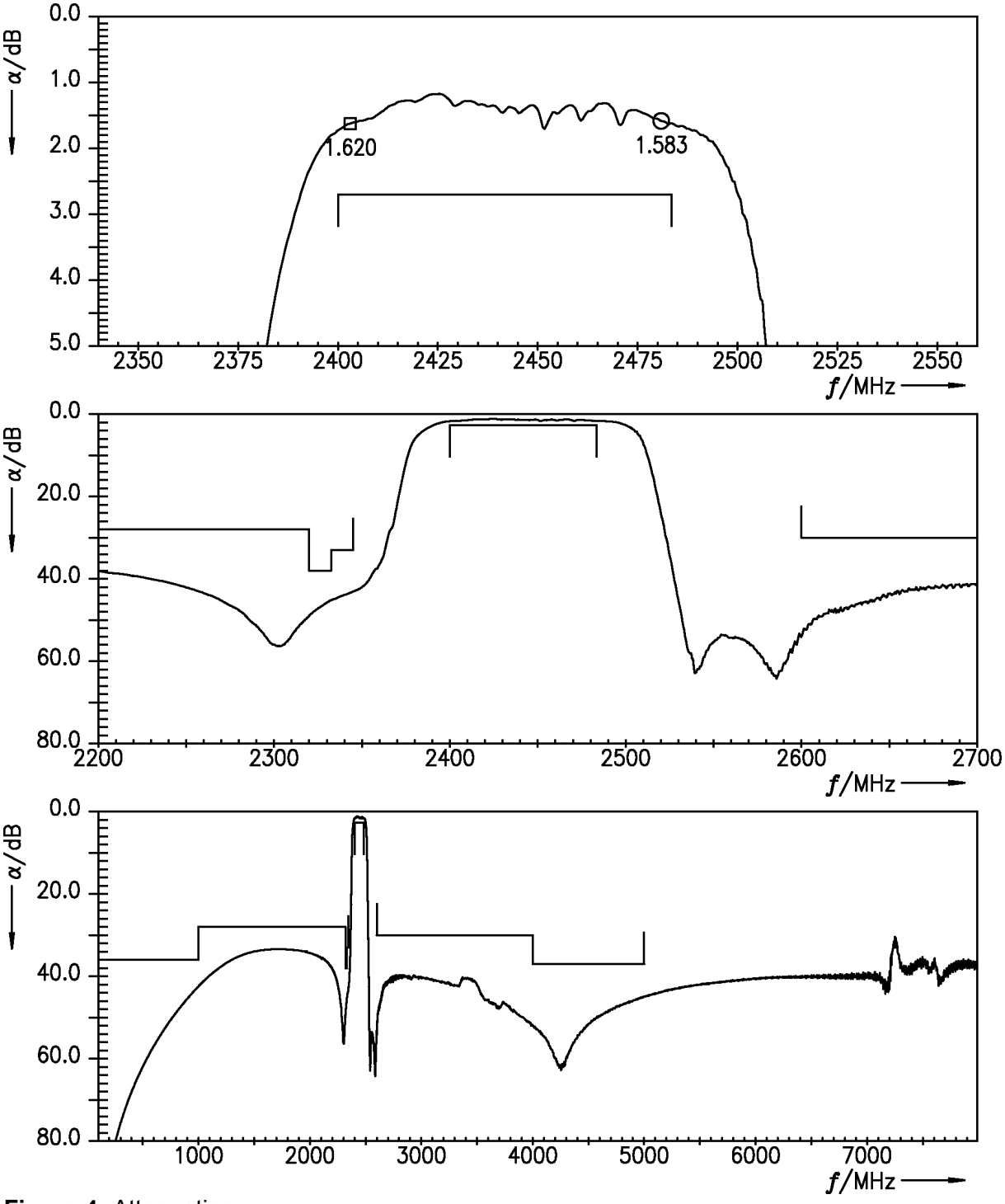

Figure 4: Attenuation.

9 Reflection coefficients

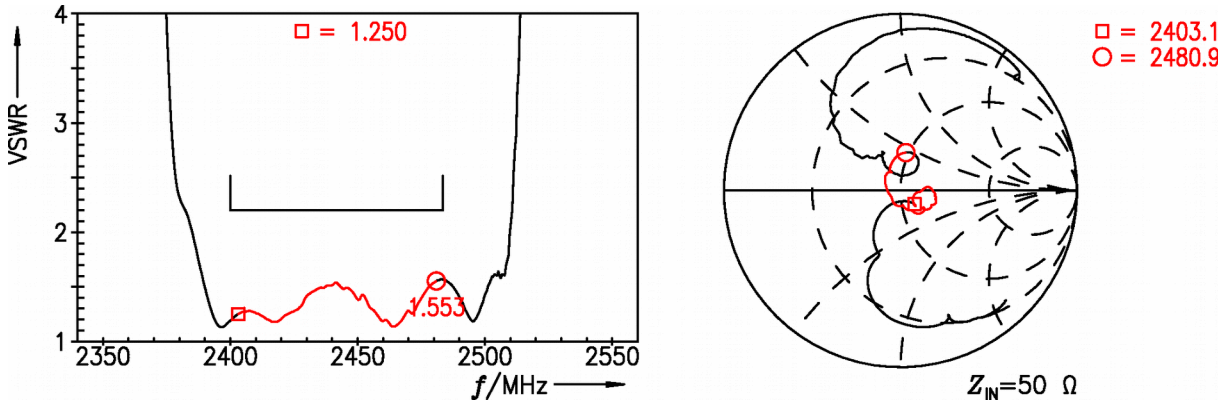

Figure 5: Reflection coefficient at IN port.

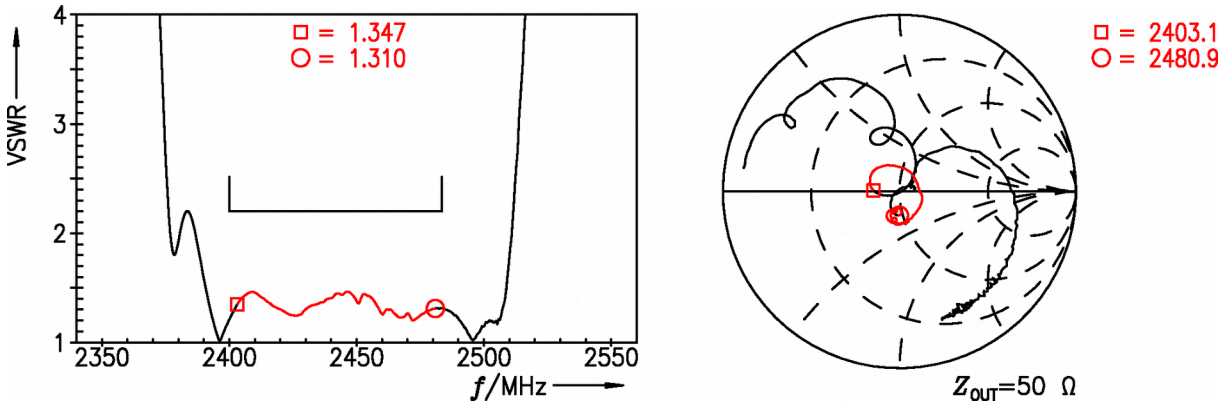

Figure 6: Reflection coefficient at OUT port.

10 Packing material

10.1 Tape

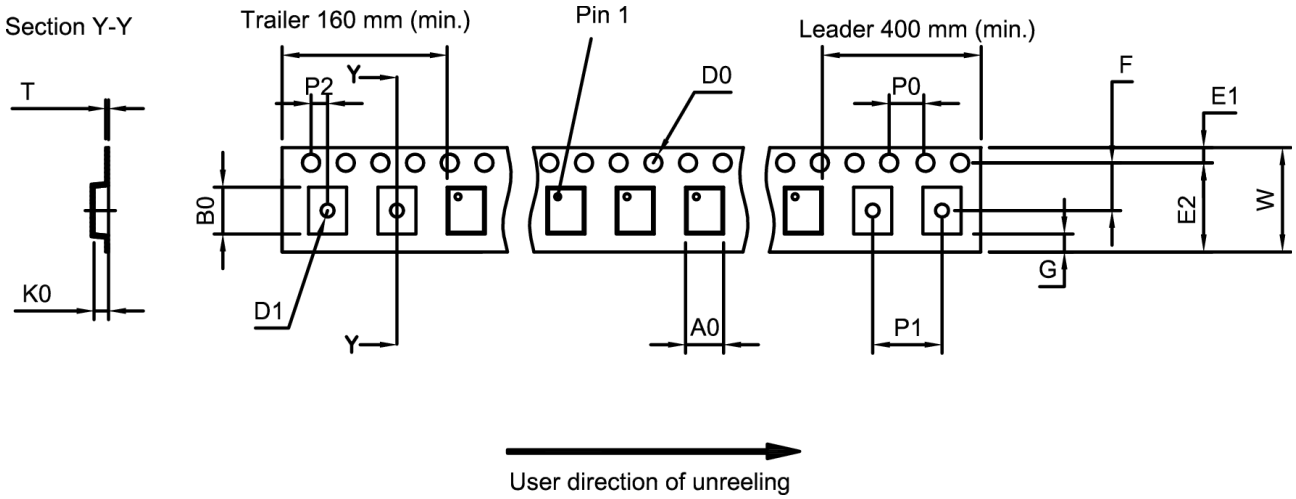

Figure 7: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A_0	$1.27_{\pm 0.05}$ mm
B_0	$1.57_{\pm 0.05}$ mm
D_0	$1.5_{+0.1/-0}$ mm
D_1	$0.5_{\pm 0.1}$ mm
E_1	$1.75_{\pm 0.1}$ mm

E_2	6.25 mm (min.)
F	$3.5_{\pm 0.05}$ mm
G	0.75 mm (min.)
K_0	$0.62_{\pm 0.05}$ mm
P_0	$4.0_{\pm 0.1}$ mm

P_1	$4.0_{\pm 0.1}$ mm
P_2	$2.0_{\pm 0.05}$ mm
T	$0.25_{\pm 0.03}$ mm
W	$8.0_{+0.3/-0.1}$ mm

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

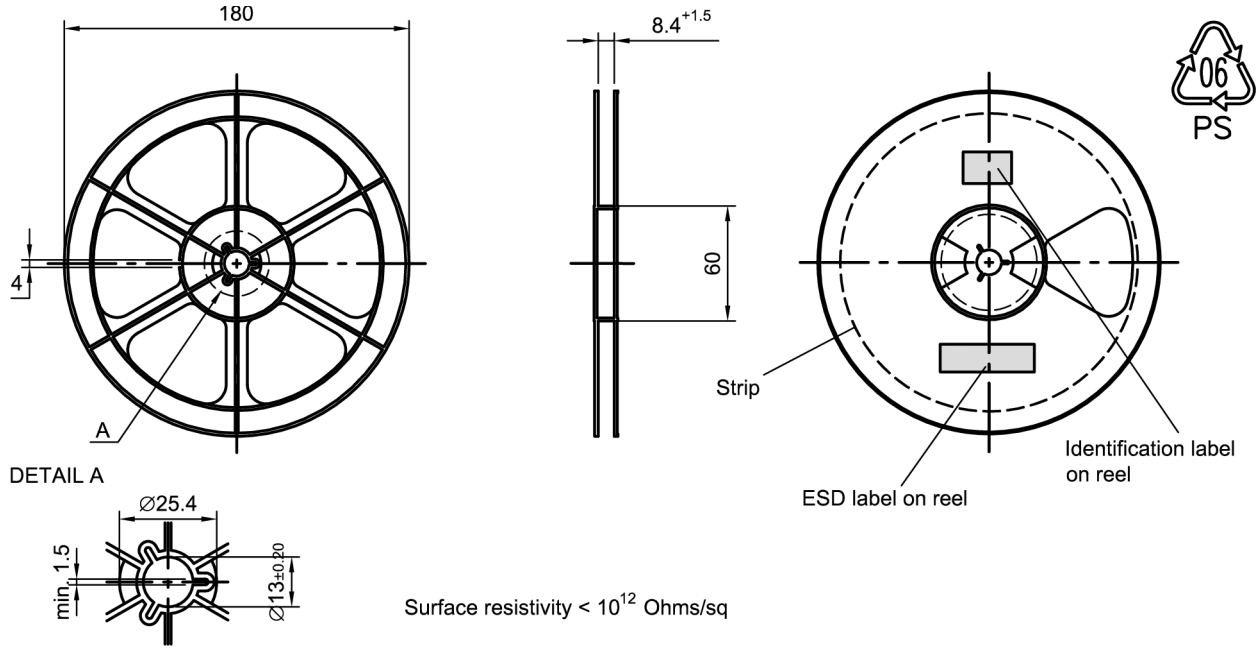

Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

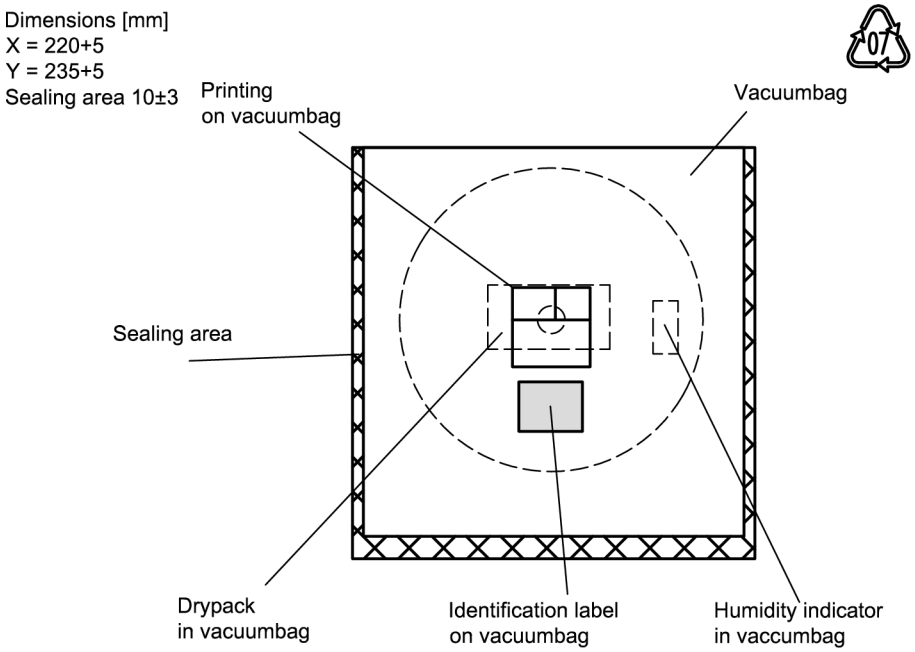

Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

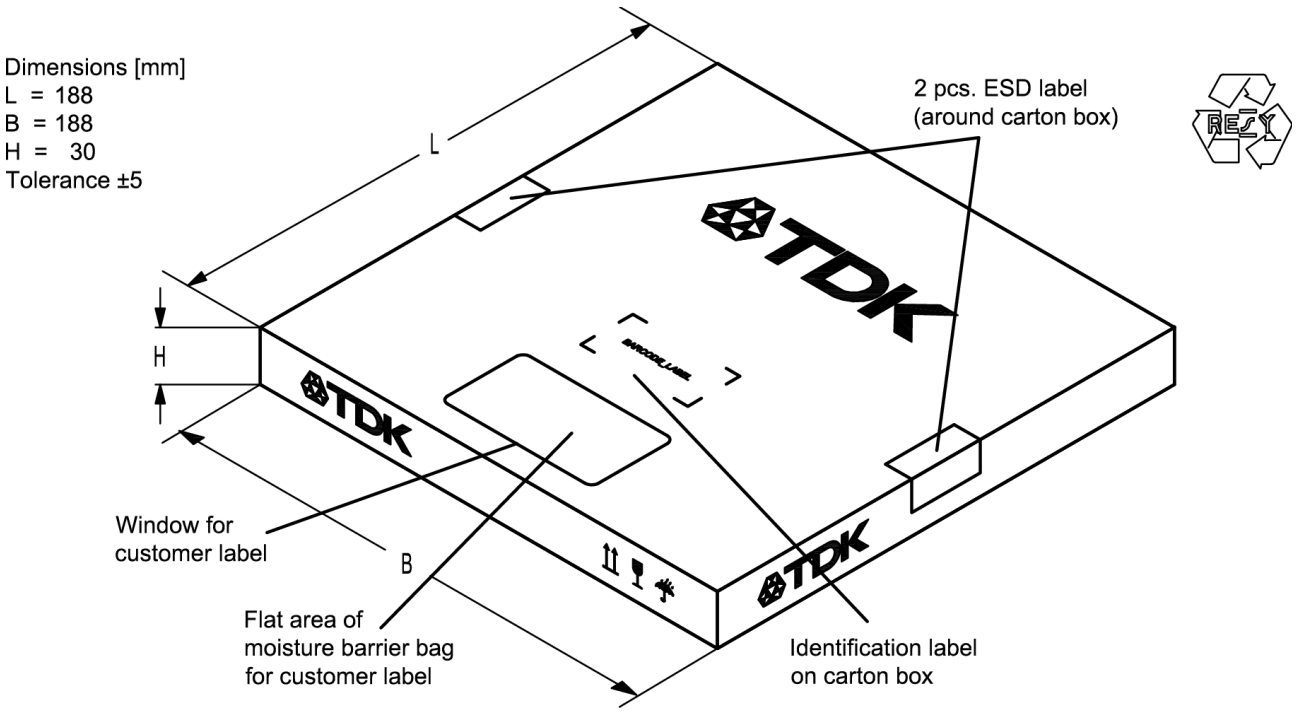

Figure 10: Drawing of folding box for reel with diameter of 180 mm.

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

- Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J	**=>**	**1234**
1 x 32^2 + **6** x 32^1 + **18 (=J)** x 32^0	**=**	**1234**

The BASE32 code for product type B4347 is 47V.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY	**=>**	**12345**
5 x 47^2 + **27 (=U)** x 47^1 + **31 (=Y)** x 47^0	**=**	**12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

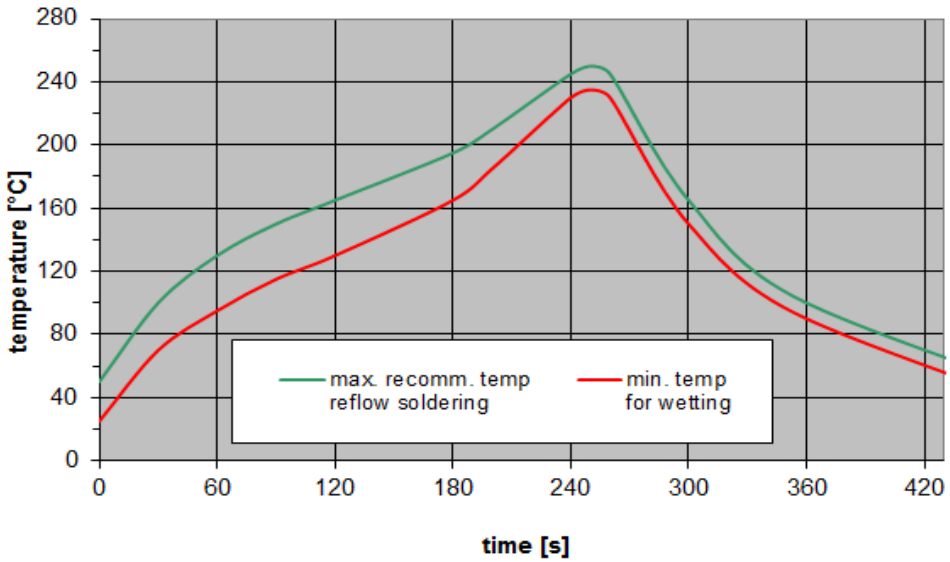

Figure 11: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 ESD protection of SAW filters

SAW filters are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies have to be applied.

In general, “ESD matching” has to be ensured at that filter port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the SAW filter has to be designed to short circuit or to block the ESD pulse.

Below three figures show recommended “ESD matching” topologies.

For wide band filters the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and SAW filter input. The required component values have to be determined from case to case.

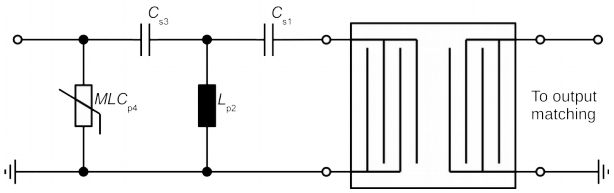

Figure 12: MLC varistor plus ESD matching.

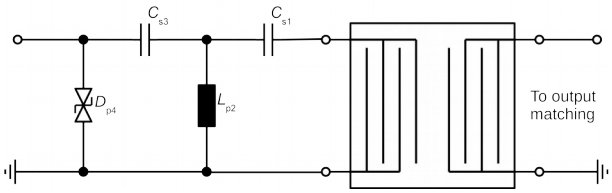

Figure 13: Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified “ESD matching” topologies can be used alternatively.

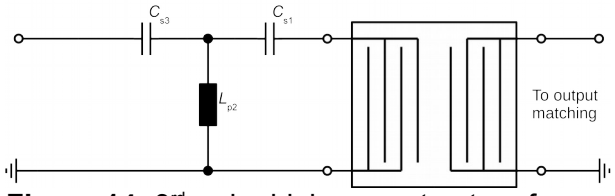

Figure 14: 3rd order high-pass structure for basic ESD protection.

In all three figures the shunt inductor L_{p2} could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to EPCOS Application report: **“ESD protection for SAW filters”.** This report can be found under www.epcos.com/rke. Click on “Applications Notes”.

14 Annotations

14.1 Matching coils

See TDK inductor pdf-catalog http://www.tdk.co.jp/tefe02/coil.htm#aname1 and Data Library for circuit simulation http://www.tdk.co.jp/etvcl/index.htm.

14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local EPCOS sales office.

15 Cautions and warnings

15.1 Display of ordering codes for EPCOS products

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Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local EPCOS sales office.

15.4 Simplified drawings

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on EPCOS internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of EPCOS, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

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